Overview

HP EliteBook 830 G8 Notebook PC



- 2. Internal Microphones (2)

Ambient Light Sensor (Optional)

- 3. Webcam LED (Optional)
- 4. Camera Shutter
- 5 HD and IR Camera (Optional)
- 6. IR Camera LEDs (Optional)

- 7. Glass Clickpad
- 8. Smartcard Reader (Optional)
- 9. Audio Combo Jack
- 10 SuperSpeed USB Type-A 5Gbps signaling rate
- 11 SuperSpeed USB Type-A 5Gbps signaling rate (Charging)
- 12. Nano Security Lock Slot (Lock sold separately)



Overview



- Power Button Key
- 2. Power Connector
- 3. HDMI 2.0b Port (Cable not included)
- 4. Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- 5. Thunderbolt™ 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)¹
- 6. SIM Card Slot (Optional)
- 7. Touch Fingerprint Sensor (Select models)

1. SuperSpeed USB 20Gbps is not available with Thunderbolt $^{\! \mathsf{TM}}$ 4.



Overview

At a Glance

- Windows 11 Pro, other Windows OS or FreeDOS preinstalled
- Premium ultraslim design with precision-crafted machined aluminum (CNC) chassis for a premium look and feel
- 11th Generation Intel[®] Core[™] i5, i7 Processors up to four-core
- Designed to support all HP docking options including the HP Universal Dock G5
- Featuring redesigned quiet HP Keyboard with the HP Programmable key and backlit options
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ultrabright displays with ambient light sensor
- Choice of displays:
 - 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 250 nits, 45% NTSC
 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 400 nits, 72% NTSC
 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 1000 nits, 100% sRGB with HP Sure View Reflect
 33.8 cm (13.3") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
- Enterprise grade security with HP Sure Sense, HP Sure Start Gen6, HP Privacy Camera, HP Sure View Reflect, HP Sure Run Gen4, HP Sure Recover Gen4 with Embedded Reimaging, HP Sure Click, SmartCard Reader and Touch Fingerprint reader
- Connectivity with optional CAT20 5G/WWAN, and Thunderbolt™ Docking (Dock sold separately)
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Choice of solid state drives up to 2 TB and DDR4 memory up to 64 GB
- Undergoes MIL-STD 810H tests¹
- Intel[®] Iris[®] X[®] Graphics

1. MIL-STD 810GH is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP EliteBook 830 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 11 Pro ²

Windows 11 Pro Education ²

Windows 11 Home – HP recommends Windows 11 Pro for business 2

Windows 11 Home Single Language – HP recommends Windows 11 Pro for business ² Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement) ²

Windows 10 Pro 1,2

Windows 10 Pro Education 1,2

Windows 10 Home – HP recommends Windows 11 Pro for business 1,2

Windows 10 Home Single Language – HP recommends Windows 11 Pro for business ^{1,2} Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) ^{1,2}

FreeDOS

- 1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- 2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS

Intel® Core™ i7-1165G7 processor (Up to 4.7 GHz frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores) ^{3,4,5,6}

Intel® Core™ i7-1185G7 (Up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores), supports Intel® vPro® Technology ^{3,4,5,6}

Intel® Core™ i5-1135G7 processor (Up to 4.2 GHz frequency with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) ^{3,4,5,6}

Intel® Core™ i5-1145G7 (Up to 4.4 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores), supports Intel® vPro® Technology ^{3,4,5,6}

Processor Family

11th Generation Intel® Core™ i7 processor (i7-1165G7)6

11th Generation Intel® Core™ i7 processor (i7-1185G7)6

11th Generation Intel® Core™ i5 processor (i5-1135G7)6

11th Generation Intel® Core™ i5 processor (i5-1145G7)6

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.



6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics7

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.38

- 7. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.
- 8. HDMI cable sold separately.

DISPLAY

Non-Touch

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD Camera (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD+IR Camera (1920x1080) 9.10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for WWAN 4G (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD Camera for WWAN 4G (1920x1080)^{9,10}

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD+IR Camera for WWAN 4G (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD+IR Camera for WWAN 5G (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 400 nits, 100% SRGB, Low Power Ambient Light Sensor for HD+IR Camera (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 400 nits, 100% SRGB, Low Power Ambient Light Sensor for HD+IR Camera for WWAN 4G (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 400 nits, 100% SRGB, Low Power Ambient Light Sensor for HD+IR Camera for WWAN 5G (1920x1080) 9,10

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD camera (1920x1080) 9,10,11,12

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD+IR camera (1920x1080) 9,10,11,12

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 1000 nits,100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD camera for WWAN 4G (1920x1080) 9,10,11,12

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 1000 nits,100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD+IR camera for WWAN 4G (1920x1080) 9,10,1,12

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP+PSR, 1000 nits,100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD+IR camera for WWAN 5G (1920x1080) 9,10,11,12



Technical Specifications

Touch

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for HD+IR camera Touch on Panel (1920x1080) 9,10,11,12

33.8 cm (13.3") diagonal FHD Bent, anti-glare UWVA eDP, 250 nits, 45% NTSC for WWAN 4G Touch on Panel (1920x1080)^{9,10,11,12}

HDMI 2.013

Support resolution up to 4K @60 Hz

- 9. FHD/HD content required to view HD images.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 12. Actual brightness will be lower with touchscreen or Sure View.
- 13. HDMI cable sold separately.

Docking station model (Sold separately)	Total number of supported displays (incl. the notebook) display)	Max resolutions supported for DP 1.4 hosts with DSC	Dock Connectors	Technical limitations / additional information For more details refer to HP Dock QuickSpecs http://h20195.www2.hp.com/v2/GetDocume nt.aspx?docname=c04168358 All information below applies to platforms running DP 1.4 with DSC
HP Thunderbolt Dock G2	Max number of displays = 4	Dual 8K@ 60Hz in high res mode	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Max displays = 4 with max resolution of 5K@ 30Hz running Thunderbolt host Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode The highest resolution for dual displays running a non-Thunderbolt host in Multifunction mode is one 5K dual cable (using both DP ports) + one 4K on USB-C DP port
HP USB-C Dock G5	3	Dual 5K@ 30Hz + 1 4K UHD (multi- function mode)	1xHDMI, 2xDP	Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode The highest resolution for running a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + one 4K on HDMI port



HP USB-C/A Universal Dock G2	3	Triple 4K UHD@ 60Hz	1xHDMI, 2xDP	In High Resolution, mode the max available is one display. This dock's best use case is triple display.
				The best resolution for dual display is two 4K UHD@ 60Hz
				Highest triple displays resolution available is three 4KUHD @60Hz using both DP and 1 HDMI port.
				Best single display is with High Resolution mode using HDMI port.
HP USB-C Travel Dock G2	1	Single 4K@ 30 Hz 4960 x 2160 (via HDMI)	1xHDMI, 1xVGA	Single external display using either HDMI or VGA

STORAGE AND DRIVES

Primary M.2 Storage

128 GB PCle®3x2 NVMe™ M.2 SSD TLC¹⁴

256 GB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴
512 GB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴
1 TB PCIe[®] Gen3 x4 NVMe[™] M.2 SSD TLC¹⁴
2 TB PCIe[®] Gen3 x4 NVMe[™] M.2 SSD TLC¹⁴

256 GB PCIe[®] NVMe[™] Value M.2 SSD¹⁴ 512 GB PCIe[®] NVMe[™] Value M.2 SSD¹⁴

256 GB PCIe® Gen3x4 NVMe™ SED TLC OPAL2¹⁴ 512 GB PCIe® Gen3x4 NVMe™ SED TLC OPAL2¹⁴

512 Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory 14,15

14. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software

15. Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.



Technical Specifications

MEMORY

Maximum Memory

64 GB DDR4-3200 SDRAM 16

Memory

64 GB DDR4-3200 SDRAM (2 x 32 GB) ¹⁶ 32 GB DDR4-3200 SDRAM (2 x 16 GB) ¹⁶ 16 GB DDR4-3200 SDRAM (2 x 8 GB) ¹⁶ 16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹⁶ 8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹⁶ 8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹⁶ 4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹⁶

Memory Slots

2 SODIMM DDR4 PC4 SODIMMS, system runs at 3200 Supports Dual Channel Memory

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, vPro® 17,18,56 Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® 17,56

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 9 19
Qualcomm® Snapdragon™ X55 5G²⁰
Near Field Communication (NFC) module ²²
HP Module with NXP NFC Controller NPC300 I2C NCI

Miracast

Native Miracast Support 21

- 17. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
- 56. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.
- 18. For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html
- 19. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions..
- 20. Qualcomm® 5G module is optional and must be configured at the factory. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G LTE not available on all products, in all regions. Backwards compatible to 4G LTE and 3G



Technical Specifications

HSPA technologies. 5G LTE module is available where carrier supported.

- 21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 22. Sold separately or as an optional feature.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen
2 integrated stereo speakers
Integrated microphone (3-Mic Array)
World- Facing microphone

Speaker Power

2W/4ohm Per speaker

Camera

720p HD camera ^{9,22} 720p HD+IR camera ^{9,22}

Sensors

Ambient light sensor Hall effect sensor HP Tamper Lock⁵⁴

- 9. FHD/HD content required to view HD images.
- 22. Sold separately or as an optional feature.
- 54. HP Tamper Lock must be enabled by the customer or your administrator.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard with Numeric Keypad, spill resistant Optional backlit keyboard and DuraKeys²³

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center

Print Screen

Power Button (with LED)

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

23. Keyboards are made from up to 65% post-consumer recycled plastic.

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen6 24 **HP Drive Lock & Automatic Drive Lock BIOS Update via Network**

HP Secure Erase 25

Absolute Persistence Module 26

HP LAN-Wireless Protection

Software

HP Connection Optimizer 27

HP Hotkey Support

myHP

HP Support Assistant 28

HP QuickDrop

HP Noise Cancellation Software

Touchpoint Customizer for Commercial

HP Notifications

HP Privacy Settings

HP Wireless Button Driver

HP Power Manager



Technical Specifications

Tile App²⁹ **HP PC Hardware Diagnostics Windows** Buy Microsoft Office (sold separately) Microsoft Defender³³ HP Smart Support⁵⁵

Manageability Features

HP Driver Packs (download) 30 HP Manageability Integration Kit Gen4 (download) 31 HP System Software Manager (SSM) (download) HP Client Catalog (download) HP Client Management Script Library (download) **HP Image Assistant (download)**

Client Security Software

HP Client Security Manager Gen7 32

Security Management

Setup password (via BIOS) HP Fingerprint Sensor 34 Support for chassis padlocks and cable lock devices HP Wolf Pro Security Edition35 HP Sure Click³⁶ HP Sure Sense⁵⁰ HP Sure Start Gen6 37 HP Sure Admin⁵¹ HP Sure Recover Gen4 38 HP Sure Run Gen4 39

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) 40

UEFI version: 2.7 Class: Class 3

24. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.

25. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

26. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/

27. HP Connection Optimizer requires Windows 10.

28. HP Support Assistant requires Windows and Internet access.

29. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information.

HP Tile will function as long as the PC has battery power.

30. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

31. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

- 32. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 33. Windows Defender Opt in and internet connection required for updates.



Technical Specifications

34. HP Fingerprint sensor is an optional feature that must be configured at purchase.

35. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

36. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details

37. HP Sure Start Gen6 is available on select HP PCs.

38. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must

38. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

39.HP Sure Run Gen4 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.

40. Firmware TPM is version 2.0.

50. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.

51. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

55. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



SMART CARD READER

Smart Card Reader (Optional)

Smart card standard PC/SC 2.0 for Windows smart card standard

Smart Card support ISO 7816 Class A and AB smart cards

Smart Card Interface Smart Card Interface with T = 0 and T = 1 support Support I2C

memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card

and AT45DB041 card via external EEPROM

Model number Alcor AU9560

FIPS 201 Compliant Yes

POWER

HP Smart 65 W External AC power adapter⁴¹

HP Smart 65 W EM External AC power adapter⁴¹

HP Smart 65 W USB Type-C® adapter41

HP Smart 45 W External AC power adapter⁴¹

HP Smart 45 W External AC power adapter, 2prong (Japan only) 41

Primary Battery

HP Long Life 3-cell, 53Wh Polymer 42,52

HP Fast Charge Technology (50% in 30 minutes)⁴³

Power Cord

3-wire plug - 1m

2-wire plug - 1m

Battery Life

Up to 14 hours and 15 minutes⁴⁴

Battery Weight

0.45lb

0.205kg

- 41. Availability may vary by country.
- 42. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 43.Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 44. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.
- 52. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.



WEIGHTS & DIMENSIONS

Product Weight

Non-Touch Starting at 2.78 lb (1.26 kg)⁴⁵

Touch Starting at 3.03 lb (1.37 kg) 45

Product Dimensions (W x D x H)12.11 x 8.05 x 0.7 in
30.78 x 20.46 x 1.79 cm

45. Weight will vary by configuration.

PORTS/SLOTS

- 2 Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4) ⁵³
- 2 SuperSpeed USB Type-A 5Gbps signaling rate (1 charging) 53
- 1 Headphone/microphone combo jack
- 1 HDMI 2.0b 13
- 1 4.5mm AC Adapter port
- 1 nano SIM card slot⁴⁶
- 1 Smartcard reader (Optional)
- 1 Nano Security Lock Slot (Lock sold separately)
- 13. HDMI cable sold separately.
- 46. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug.
- 53. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.



Technical Specifications

SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90 day software limited warranty options depending on country.

Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/

for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 47

47. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

SYSTEM UNIT

Stand-Alone Power Nominal Operating Voltage 19.5V Requirements (AC Power) Average Operating Power 1.825W **Integrated Graphics** Yes

Discrete Graphics N/A

Max Operating Power **UMA < 45W**

32° to 95° F (0° to 35° C) **Temperature** Operating

> Non-operating 41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity Operating 10% to 90%, non-condensing

> 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature Non-operating

Shock Operating 40 G, 2 ms, half-sine

> Non-operating 200 G. 2 ms. half-sine

Random Vibration Operating 0.75 grms

Non-operating 1.50 grms

Altitude (unpressurized) Operating -50 to 10.000 ft (-15.24 to 3.048 m)

> Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard UL Certifications **CSA** Yes

> **FCC Compliance** Yes

ENERGY STAR® qualified Select models⁴⁸

EPEAT® 2019 EPEAT 2019 Gold in United States 49

ICES Yes **Australia** Yes **NZ A-Tick Compliance** Yes CCC Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes **GOST** Yes Yes

Saudi Arabian Compliance

(ICCP)

SABS Yes

48. Configurations of the HP EliteBook 830 G7 that are ENERGY STAR® qualified are identified as HP EliteBook 830 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

49. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit www.epeat.net for more information.



Technical Specifications

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT [□] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO			
Sustainable Impact Specifications	Ocean-bound plastic in speaker enclosure 37.9% post-consumer recycled plastic External Power Supply 90% Efficiency			
	 Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable • Recycled Pl cushions Bulk packaging available 			
System Configuration	The configuration used for the Ener Notebook model is based on a "Typi		ise Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)	7.25 W	7.21 W	7.23 W	
Normal Operation (Long idle)	1.73 W	1.49 W	1.94 W	
Sleep	1.73 W	1.49 W	1.94 W	
Off	0.45 W	0.41 W	0.37 W	
	Note: Energy efficiency data listed is for a family. HP computers marked with the Environmental Protection Agency (Edoes not offer ENERGY STAR® computypically configured PC featuring a house operating system.	the ENERGY STAR® Logo are com PA) ENERGY STAR® specification liant configurations, then energy nard disk drive, a high efficiency p	pliant with the applicable U.S. s for computers. If a model family r efficiency data listed is for a power supply, and a Microsoft	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	25 BTU/hr	25 BTU/hr	25 BTU/hr	
Normal Operation (Long idle)	6 BTU/hr	6 BTU/hr 5 BTU/hr		
Sleep	6 BTU/hr	5 BTU/hr	7 BTU/hr	
Off	2 BTU/hr 1 BTU/hr 1 BTU/hr *NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level attained for one hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.5		18	
Fixed Disk – Random writes	2.7 25			



Technical Specifications

Optical Drive –					
Sequential reads	This product can be upgraded possibly outending its useful life by several years. Upgradeable				
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the			lueable	
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product is 95.7% recycle-able when properly disposed of at end of life. 				
Packaging Materials	External:	PAPER/Corrugated		220 g	
	Internal:	PAPER/Paperboard		41 g	
		PAPER/Molded Pulp		177 g	
		PLASTIC/Polypropylene - PP		3 g	
		PLASTIC/Polyethylene low dens		14 g	
	The plastic packaging material contains at least 0% recycled content. The corrugated paper packaging materials contains at least 55.3% recycled content.				
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.				
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Bis(2-Ethylhexyl) phthalate (DEHP) - Benzyl butyl phthalate (BBP) - Dibutyl phthalate (DBP) - Diisobutyl phthalate (DIBP)				



Technical Specifications

recillicat Specific	Lations
	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently handled
	or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in
	packaging materials.
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	 Design packaging materials for ease of disassembly.
	 Maximize the use of post-consumer recycled content materials in packaging materials.
	 Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle
and Recycling	your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales
	office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The FILMESS divertive (2002/05/55) we exist a second of the second of the second information for
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions)
	is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions
	may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who
	integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	To more information about in 3 commitment to the environment.
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	Percentage of ocean-bound plastic contained in each component varies by product
	Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018
	standard.
	External power supplies, WWAN modules, power cords, cables and peripherals excluded.
	100% outer box packaging and corrugated cushions made from sustainably sourced certified and rescaled file are
	and recycled fibers.
	Fiber cushions made from 100% recycled wood fiber and organic materials. Plactic sushions are made from > 00% recycled plactic.
	Plastic cushions are made from >90% recycled plastic.



DISPLAYS

1. Actual brightness will be lower with touchscreen or Sure View.

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch FHD (1920 x 1080) Anti-Glare WLED UWVA 45% cg 250nits eDP 1.2 w/o PSR bent NWBZ Outline Dimensions (W x H x D) 300.56 x 177.77 mm (max) (FPC folding included)

Active Area 293.76 x 165.24 mm (typ.)

Weight 260 g (max)
Diagonal Size 13.3 inch

Thickness 3.0 mm/ 5.0 mm (PCB) (max)

Interface eDP 1.2 (2lane)
Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Stripe
Backlight LED

Color Gamut Coverage NTSC 45% **Color Depth** 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch FHD (1920.x 1080) Anti-Glare WLED UWVA 45% cg 250nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ

 Outline Dimensions (W x H x D)
 300.56 x 177.77 mm (max)

 Active Area
 293.76 x 165.24 mm (typ.)

Weight 260 g (max)
Diagonal Size 13.3 inch

Thickness 3.0 mm/ 5.0 mm (PCB) (max)

Interface eDP 1.2

Surface Treatment Anti-Glare On-cell

Touch Enabled Yes

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits1

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Stripe
Backlight LED
Color Gamut Coverage NTSC 45%

Color Depth 6 bits (Hi FRC supportive w/ condition to enable)

Viewing Angle UWVA 85/85/85



Panel LCD 13.3 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100% cg 400nits eDP 1.4+PSR2 bent LP NB2Y Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max) (FPC folding included)

Active Area 293.76 x 165.24 mm (typ.)

Weight 175 g (max)
Diagonal Size 13.3 inch

Thickness 2.0 mm / 3.8 mm (PCB) (max) Interface eDP 1.4 w/ PSRII (2 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio1500:1(typ.)Refresh Rate60 HzBrightness400 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Stripe

Backlight LED

Color Gamut Coverage SRGB 100% (NTSC 72%)

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3-in FHD (1920 Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max)

x 1080) Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View Reflect NB2Y bent Active Area 293.76 x 165.24 mm (typ.)

Weight220 g (max)Diagonal Size13.3 inchThickness3.9 mm (max)InterfaceeDP 1.4 + PSRSurface TreatmentAnti-glare (AG)

Touch Enabled No

Contrast Ratio 1500:1 (typ.)
Refresh Rate 60 Hz
Brightness 1000 nits 1

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 100% sRGB **Color Depth** 8 bits

Viewing Angle UWVA 85/85/85



Technical Specifications

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

SSD 128GB 2280 PCIe-3x2 Three Laver Cell Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X2

 Maximum Sequential Read
 Up to 1400 ~ 2100 MB/s

 Maximum Sequential Write
 Up to 800 ~ 1200 MB/s

Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security (Option); TRIM; L1.2

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up to 3100 ~ 3500 MB/s

 Maximum Sequential Write
 Up to 2700 ~ 3037 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up to 2800 ~ 3500 MB/s

 Maximum Sequential Write
 Up to 1600 ~ 2200 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2



SSD 256GB 2280 PCIe NVMe Form Factor

Value

M.2 2280 256 GB Capacity **NAND Type** Value

Heiaht 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 q) Interface PCIe NVMe Gen3X2 **Maximum Sequential Read** Up to 2100 ~ 2400 MB/s **Maximum Sequential Write** Up to 950 ~ 1400 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

M.2 2280

Features ATA Security (Option); TRIM; L1.2

SSD 256GB 2280 PCle-3x4 **NVMe Self Encrypted OPAL2** Three Layer Cell

SSD 2TB 2280 PCIe-3x4

NVMe Three Layer Cell

single-sided

Form Factor Capacity **NAND Type**

256 GB TLC Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm) Weight 0.02 lb (10 q) Interface PCIe NVMe Gen3X4 **Maximum Sequential Read** Up to 2800 ~ 3500 MB/s **Maximum Sequential Write** Up to 1663 ~ 2200 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

Features

Form Factor M.2 2280

Capacity 2 TB **NAND Type** TLC

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3X4 **Maximum Sequential Read** Up to 3100 ~ 3500 MB/s **Maximum Sequential Write** Up to 2800 ~ 3000 MB/s

Logical Blocks 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

ATA Security; TRIM; L1.2 **Features**



Technical Specifications

SSD 512GB 2280 M2 PCle-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up to 3100 ~ 3500 MB/s

 Maximum Sequential Write
 Up to 2100 ~ 2956 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512GB 2280 PCle NVMe Form Factor

Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X2

 Maximum Sequential Read
 Up to 1500 ~ 2400 MB/s

 Maximum Sequential Write
 Up to 1000 ~ 1750 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

SSD 512GB 2280 PCle-3x2x2 Form Factor M.2 2280 NVMe+SSD 32GB 3D Xpoint Capacity 512 GB

 NAND Type
 QLC+3D XPoint

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

InterfacePCIe NVMe Gen3X2X2Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1300 MB/sLogical Blocks1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2



Technical Specifications

SSD 512GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up to 3100 ~ 3500 MB/s

 Maximum Sequential Write
 Up to 2400 ~ 2956 MB/s

Logical Blocks 1,000,215,215

Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (Option); TCG Opal 2.0; TRIM; L1.2



NETWORKING/COMMUNICATIONS

Intel® Wi-Fi® 61 AX201 + Wireless LAN Standards IEEE 802.11a IEEE 802.11b BT5 (802.11ax 2x2, vPro®, IEEE 802.11q supporting gigabit file IEEE 802.11n transfer speeds)5 vPro®

IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability Features Wi-Fi 6 technology

Frequency Band •802.11b/q/n/ax

2.402 - 2.482 GHz •802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

> •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

•802.11n: max 300 Mbps •802.11ac: 1733 Mbps •802.11ax: max 2.4 Gbps

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ •IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

 WPA2 certification WPA3 certification •IEEE 802.11i WAPI

Network Architecture

Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +17dBm minimum

> • 802.11g: +16 dBm minimum • 802.11a: +17dBm minimum

 802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +13dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT160(5GHz): +10dBm minimum 802.11ax HE40(2.4GHz): +12dBm minimum 802.11ax HE80(5GHz): +10dBm minimum



• 802.11ax HE160(5GHz): +10dBm minimum

Power Consumption •Transmit mode:2.0 W

•Receive mode:1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode:50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

•Radio disabled:8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11ac, MCS0 (VHT80): -84dBm maximum
802.11ac, MCS9 (VHT80): -59dBm maximum
802.11ac, MCS9 (VHT160): -58.5dBm maximum
802.11ax, MCS11(HE40): -57dBm maximum
802.11ax, MCS11(HE80): -54dBm maximum
802.11ax, MCS11(HE160): -53.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating Operating: 14° to 158° F (-10° to 70° C)

Non-operating Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating Operating: 10% to 90% (non-condensing)

Non-operating Non-operating: 5% to 95% (non-condensing)

Altitude Operating Operating: 0 to 10,000 ft (3,048 m)

Non-operating Non-operating: 0 to 50,000 ft (15,240 m)

LED Amber – Radio OFF; LED White – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1/5.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)"

Signaling Data Rate Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW



Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported Link Topology

Certifications

Microsoft Windows Bluetooth Software

Power Management

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo

Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE LE Long Range

Security & Manageability Intel® vPro® support with appropriate Intel® chipset components

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Intel® Wi-Fi® 61 AX201 + BT5 (802.11ax 2x2, nonvPro®, supporting gigabit file transfer speeds)⁵ non-vPro®

Wireless LAN Standards IEEE 802.11a

> IEEE 802.11b IEEE 802.11g IEEE 802.11n

IEEE 802.11ac IEEE 802.11ax

IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r

IEEE 802.11v

Interoperability Features Wi-Fi 6 technology

Frequency Band •802.11b/q/n/ax

> 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

> •802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

•802.11n: max 300 Mbps •802.11ac: 1733 Mbps •802.11ax: max 2.4 Gbps

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ •IEEE and WiFI compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

 WPA2 certification WPA3 certification •IEEE 802.11i •WAPI

Network Architecture

Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +17dBm minimum

• 802.11q: +16 dBm minimum 802.11a: +17dBm minimum

• 802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +13dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum • 802.11ac VHT160(5GHz): +10dBm minimum • 802.11ax HE40(2.4GHz): +12dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum • 802.11ax HE160(5GHz): +10dBm minimum



Technical Specifications

Power Consumption •Transmit mode2.0 W

•Receive mode1.6 W

•Idle mode (PSP)180 mW(WLAN Associated)
•Idle mode50 mW(WLAN unassociated)

•Connected Standby 10mW

•Radio disabled8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11ac, MCS0 (VHT80): -84dBm maximum
802.11ac, MCS9 (VHT80): -59dBm maximum
802.11ac, MCS9 (VHT160): -58.5dBm maximum
802.11ax, MCS11(HE40): -57dBm maximum
802.11ax, MCS11(HE80): -54dBm maximum
802.11ax, MCS11(HE160): -53.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating Operating: 14° to 158° F (–10° to 70° C)

Non-operating Non-operating: –40° to 176° F (–40° to 80° C)

Humidity Operating Operating: 10% to 90% (non-condensing)

Non-operating Non-operating: 5% to 95% (non-condensing)

Altitude Operating Operating: 0 to 10,000 ft (3,048 m)

Non-operating Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber Radio OFF; LED Off – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1/5.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW



Peak (Rx): 230 mW Selective Suspend: 17 mW

Bluetooth Software Supported Link Topology

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

Microsoft Windows Bluetooth Software

UL, CSA, and CE Mark

Bluetooth Software Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 –Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo

Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE LE Long Range

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Qualcomm® Snapdragon™ X55 5G ¹ modem Technology/ Operating bands WCDMA/HSDPA/HSUPA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 9: 1750 to 1785 MHz(UL), 1845to 1880 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) 5GNR Sub 6GHZ n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) n41: 2496 to 2690 MHz (UL/DL) n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)



Technical Specifications

Wireless protocol standards 5GNR Air Interface

l 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput - 4 × 4 MIMO across

5x CA

200 Mbps uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA

R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands GPS: L1 (1575.42MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42)

Maximum data rates 5G sub 6G: 3.8 Gbps

LTE: ue-CategoryDL 20, (DL : 2 Gbps) ue-CategoryUL 18 , (UL: 200Mbps)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

HSPA+: 23.5 dBm

Maximum power consumption 5G Sub 6: 2500 mA

LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 8 g

Dimensions

(Length x Width x Thickness) 42 mm × 30 mm × 2.6 mm

1. Qualcomm® 5G module is optional and must be configured at the factory. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G LTE not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G LTE module is available where carrier supported.



Intel® XMM™ 7360 LTE-Advanced CAT 9¹ **Technology/Operating** FDD LTE:

bands 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4),

850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1450 (Band 21), 850 (Band 26) 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band

66) TDD LTE:

2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41)

HSPA+:

2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900

(Band 8)

Wireless protocol standards 3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

Maximum data rates LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6.2 g

Dimensions

(Length x Width x

Thickness) 42 x 30 x 2.3 mm

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

NXP NPC300 Near Field Communication Module

Dimensions (L x W x H) Module 17 mm by 10 mm by 2.0 mm

Chipset NPC300 System interface I2C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type 3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 15693 MIFARE 1K MIFARE 4K



MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-VICC) ISO/IEC 14443 A

Mode (1)

ISO/IEC 14443 B and B'

MIFARE

FeliCa

13.56 MHz

Frequency

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating temperature Storage temperature

-20°C to 125°C

0°C to 70°C

Humidity

10-90% operating 5-95% non-operating

Supply Operating voltage

2.97 to 5.5 Volts

I/O Voltage

1.8V or 3.3V

Power Consumption

Mode

Power Consumption, Typical (2)

(Booster enable, VBAT= 3.3V, $VCC_BOOST = 5V$)

> **Polling** 7.3 mA

Detected Test Tag Type 1 32.9 mA **Detected Test Tag Type 2** 7.7 mA Detected Test Tag Type 3 79.2 mA

Detected Test Tag Type 4

64.9 mA

Antenna

Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.



POWER

AC Adapter 45 Watt Smart Dimensions (H x W x D) nPFC Standard Barrel 4.5mm Right Angle 1.8m

95x40x26.8mm Weight unit: 200a +/- 10a

Not including power cord. Power cord varies by country

87.74 % at 115 Vac and 88.4 % at 230Vac Input **Input Efficiency**

> Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output **Output power** 45 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0 A

Connector 4.5 mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety

Certifications *CE Mark - full compliance with LVD and EMC directives

> * Worldwide safety standards - IEC60950-1 and/or IEC62368-1. EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

SELV:

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B,

CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart Dimensions (H x W x D) nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong

95x40x26.8mm

Weight unit: 200a +/- 10a

Not including power cord. Power cord varies by country

Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230Vac Input

> Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output **Output power** 45 W

> DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector 4.5 mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature



Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications

9.

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

SELV;

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B,

CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Slim USB type C Straight 1.8m Dimensions (H x W x D) 88x53.5x21mm

Weight unit: 220 q +/- 10 q

Not including power cord. Power cord varies by country

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65 W

DC output 5V/9V/12V/15V/20V
Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector USB Type C

Environmental Design Operating 32°Fto 95°F (Ooto 35°C)

temperature

Non-operating (storage) -4°Fto 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

Storage Humidity 5

EMI and Safety Eg Certifications *C

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

SELV:

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B,

CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



AC Adapter 65 Watt nPFC Standard USB type C Straight 1.8m

Dimensions (H x W x D) 90.0x51x28.5mm

Weight unit: 250 q +/- 10 q

Not including power cord. Power cord varies by country

Input 81.5% min at 115 Vac/ 230Vac @ 5V/3A Input Efficiency

> 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

1.6 A at 90 VAC and maximum load Input AC current

Output **Output power**

> DC output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit <8.0 A Max.

Connector USB type C **Environmental Design** Operating

temperature

32°F to 95°F (0°to 35°C)

Non-operating (storage)

temperature -4°F to 185°F (-20°to 85°C) **Altitude** 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

Max. 1.7 A at 90 Vac

SELV;

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B,

CISPR32 Class B. CCC. NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart Dimensions (H x W x D) nPFC EM Barrel 4.5mm **New EM**

102x55x30mm

Weight

Output

unit: 250 q +/- 10 q

Not including power cord. Power cord varies by country

Input **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230Vac

Input AC current

Input frequency range 47 ~ 63 Hz

Output power 65 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A

Connector 4.5 mm Barrel Type

Environmental Design Operating

32°F to 95°F (0°to 35°C) temperature



Non-operating (storage)

temperature

-4°F to 185°F (-20°to 85°C)

Altitude

0 to 16.400 ft (0 to 5000m)

Humidity

20% to 95%

Storage Humidity

10% to 95%

EMI and Safety Certifications

Ea:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

SELV:

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B.

CISPR32 Class B. CCC. NOM-001 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart Dimensions (H x W x D) nPFC Standard Barrel 4.5mm Right Angle 1.8m

90x51x28.5mm

Weight

unit: 230 q +/- 10 q

Not including power cord. Power cord varies by country

Input

Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output

Output power 65 W DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0 A

Connector

4.5 mm Barrel Type

Environmental Design

Operating temperature

32°F to 95°F (0°to 35°C)

Non-operating (storage)

temperature

-4°F to 185°F (-20°to 85°C)

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,

SELV:

Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B.

CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications

Battery CC 3 Cell 53 Wh 53 Dimensions (H x W x D)

Long Life -PL Fast Charge

7.3 x 52.9 x 267.11mm (0.287 x 2.082 x 10.516 inch)

Weight 0.205 kg (0.45 lb)

Cells/Type 3cell Lithium-Ion Polymer cell

Energy Voltage 11.55 V

Amp-hour capacity 4.59 Ah

Watt-hour capacity¹ 53 Wh

Temperature

Operating (Charging) 32° to 113° F (0° to 45° C)
Operating (Discharging) 14° to 140° F (-10° to 60° C)

Fuel Gauge LED N/A

Warranty Depends on system offering

Optional Travel Battery No.

Available

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

COUNTRY OF ORIGIN

China



Options and Accessories (Sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Case (up to 15.6")	2SC66AA
	HP Business Slim Top Load (up to 14.1" x .75" thick)	2SC65AA
	Prelude Pro Top Load	1X645AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock w/ Combo Cable (230W)	3TR87AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP TB Dock 230W G2 Cable	3XB95AA
	HP USB-C Mini Dock	1PM64AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
Input/Output	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
• • •	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Premium Keyboard	Z9N41AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP USB Travel Mouse	G1K28AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA
	HP UC Wireless Duo Headset	W3K09AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to VGA	H4F02AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB to Gig RJ45 Adapter	N7P47AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP Elite USB-C Hub	4WX89AA



Options and Accessories (Sold separately and availability may vary by country)

Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
	HP USB-C Essential Power Bank	3TB55AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 256 GB PCI-e 3x4 NVMe M.2 SSD	
	HP 512 GB PCI-e 3x4 NVMe M.2 SSD	
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Sure Key Cable Lock	6UW42AA
	July Lable Book	3347127111



Change Log

Date of change:	Version History:		Description of change:
December 11, 2020	V1 to V2	Update	Battery Life, Ports, Environmental Data
January 27, 2021	V2 to V3	Update	USB ports to new industry standards.
February 4, 2021	V3 to V4	Added	Processors
February 8, 2021	V4 to V5	Updated	Smartcard Reader
February 10, 2021	V5 to V6	Added	Environmental Data
February 17, 2021	V6 to V7	Update	Processors section
March 9, 2021	V7 to V8	Update	Audio and Multimedia section
April 16, 2021	V8 to V9	Updated	Memory Section and Input/ Output Section Updated
April 23, 2021	V9 to V10	Added	BIOS information in Software section
April 29, 2021	V10 to V11	Updated	TPM 2.0
May 6, 2021	V11 to V12	Removed	Processors base frequency/Added HP Smart Support
May 20, 2021	V12 to V13	Removed	HP Thunderbolt Dock 230W G2
May 27, 2021	V13 to V14	Updated	HP Pro Security Edition to HP Wolf Pro Security Edition
June 11, 2021	V14 to V15	Removed	HP WorkWell from Software and Security section
September 9, 2021	V15 to V16	Updated	Techspecs in Networking and Power section
November 11, 2021	V16 to V17	Updated	Windows 10 with Free upgrade to Windows 11 when available in OS
			section and footnote.
November 17, 2021	V17 to V18	Update	Networking Qualcomm® 5G Disclaimers
December 8, 2021	V18 to V19	Update	OS footnotes and Wi-Fi 6 disclaimers
December 14, 2021	V19 to V20	Update	Windows OS section

Copyright © 2021 HP Development Company, L.P. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core and Intel vPro are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries. DisplayPort™ and the DisplayPort™ logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. USB Type-C® and USB-C® are trademarks of USB Implementers Forum. ENERGY STAR is a registered trademark of the U.S. Environmental Protection Agency. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries.

